



100% Material Declaration Data Sheet for 7-Series (Artix) FBG676 RoHS 6/6

PK860(v1.0) January 19, 2017

Average Weight : 2.7927 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	0.237267	8.50%
					0.237267	
Bump					0.009525	0.34%
	Tin	7440-31-5	98.20	basis	0.009354	
	Silver	7440-22-4	1.80	basis	0.000171	
Underfill					0.035000	1.25%
	Bisphenol F type liquid epoxy	9003-36-5	15.00	basis	0.005250	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.003500	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001750	
	Amine type hardener	trade secret	10.00	basis	0.003500	
	Silicon dioxide	60676-86-0	58.00	filler	0.020300	
	Carbon black	1333-86-4	1.00	color agent	0.000350	
Additives	trade secret	1.00	additives	0.000350		
Solder ball					0.564707	20.22%
	Tin	7440-31-5	96.50	Main material	0.544942	
	Silver	7440-22-4	3.00	Main material	0.016941	
	Copper	7440-50-8	0.50	Main material	0.002824	
Substrate					1.946201	69.69%
	Copper	7440-50-8	37.45		0.728852	
	Tin	7440-31-5	0.97		0.018878	
	Silver	7440-22-4	0.03		0.000584	
	Core	N/A	48.21		0.938264	
	ABF	N/A	10.94		0.212914	
	Solder Mask	N/A	2.40		0.046709	

Revision History

Date	Version	Description of Revisions
1/19/2017	1.0	Initial Xilinx release.

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